

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application Serial No. 10/735,355
Filing Date December 12, 2003
Inventorship Zhongze Wang
Assignee Micron Technology, Inc.
Group Art Unit 2812
Examiner J. Kennedy
Attorney's Docket No. MI22-2457
Title Wafer Bonding Method of Forming Silicon-On-Insulator Comprising
Integrated Circuitry

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References - See Attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. Copies of the cited art are not included (1276 Off. Gaz. Pat. Off 55, 05 August 2003). No admission is made regarding whether all the submitted references are prior art.

08/19/2005 CNGUYEN2 00000012 10735355

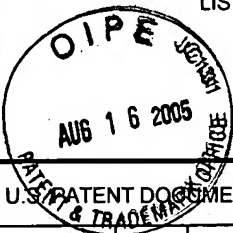
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Respectfully submitted,

Dated: August 16, 2005

By: Jennifer J. Taylor
Jennifer J. Taylor, Ph.D.
Reg. No. 48,711

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-2457		SERIAL NO. 10/735,355	
 <p>LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)</p>				APPLICANT: Zhongze Wang			
				FILING DATE December 12, 2003		GROUP 2811	
U.S. PATENT DOCUMENTS							
*Examiner's Initials	AA	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	6,245,636	6/12/2001	Maszara			
	AB	2002/0048844	4/25/2002	Sakaguchi			
	AC	2002/0034844	3/21/2002	Hsu et al.			
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
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<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>							